



W. Lohmann, DESY

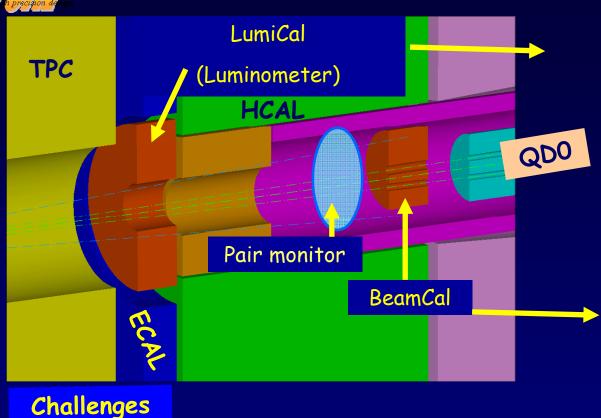
- Challenges and Design
- Sensors and Sensor Studies
- FE ASICS development
- Data Transfer, Infrastructure

Labs involved: Argonne, BNL, Vinca Inst, Belgrade, Bukharest Univ. of Colorado, Cracow UST, Cracow INP, JINR, Royal Holloway, NCPHEP, Prague(AS), LAL Orsay, Tuhoku Univ., Tel Aviv Univ., West Univ. Timisoara, Yale Univ. DESY (Z.)

Associated: Stanford Univ. IKP Dresden Guests from : CERN

Novembre 2008

# Calorimeters in the very forward region (example ILD, 14 mrad)

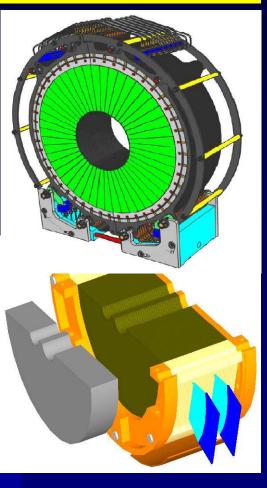




LumiCal: -control of position on ~100 µm level -control of the inner acceptance radius on ~µm level

BeamCal: -radiation hard sensors (~10 MGy/year) -compact (smallest possible Moliere radius) -readout after each BX Both:

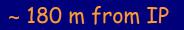
Pair monitor: fast pixel device, harsh radiation conditions





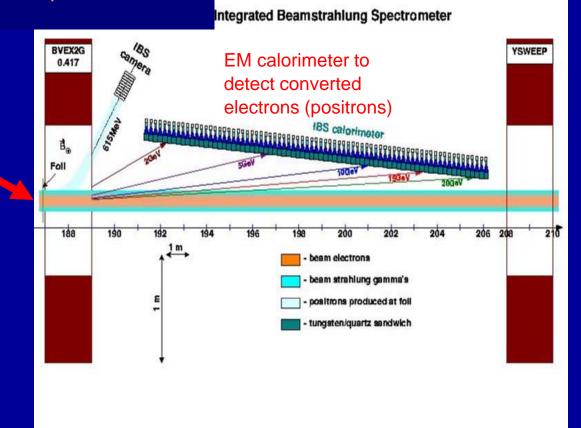


### one more calorimerter, GamCal



< 5 mrad aperture (beamstr photons)

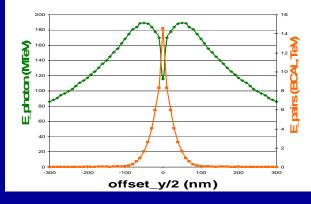
Thin foil to convert beamstrahlung photons





#### **Dedicated Functions**

E\_pairs (BCAL) and E\_photon

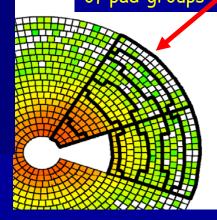


### BeamCal, Pair Monitor, GamCal

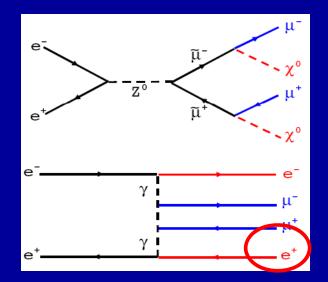
Fast feedback for beam tuning, beam diagnostics using beamstrahlung;

Beamparameter determination on percent level

# Fast analog summation of pad-groups



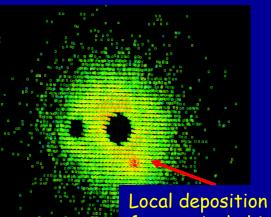
BNL, DESY, JINR,



BeamCal Hermeticity, Electron veto at low angles, Mask for the inner

Mask for the inner detectors

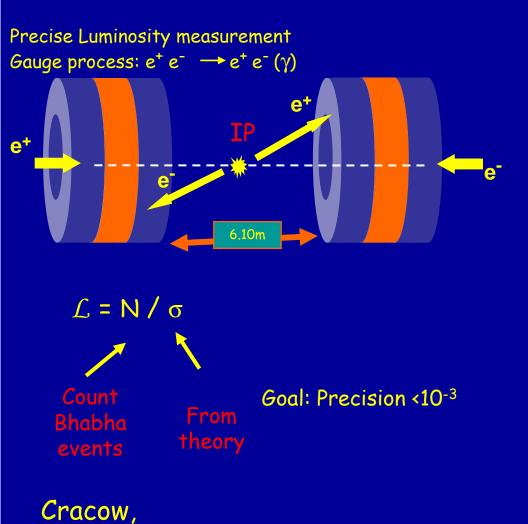
UCB



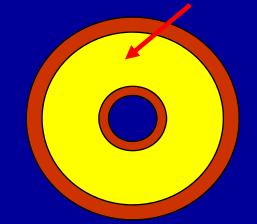
Local deposition from a single high energy electron

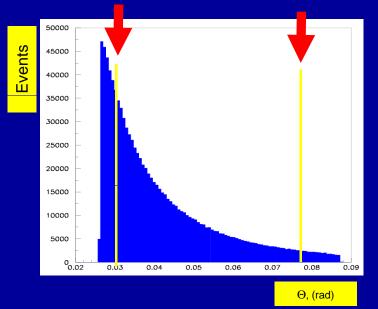


#### **Dedicated Functions**



Fiducial volume for event counting



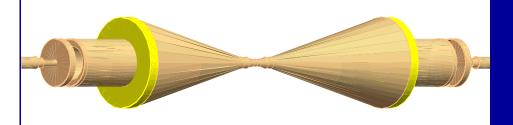


Tel Aviv

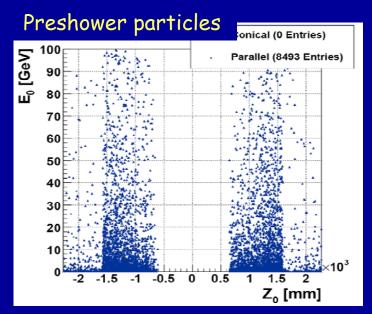


### Beampipe Design

#### Conical, central part Be



#### Pro: minimum material in front of LumiCal Contra: vacuum, HOM, mechanics



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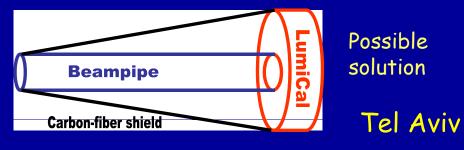
#### Cylindrical, full Be, inner radius 5.5 cm (14 mrad crossing angle)



Pro: facilitates mechanics, vacuum Contra:material in front of LumiCal, preshowering, electron measurement?

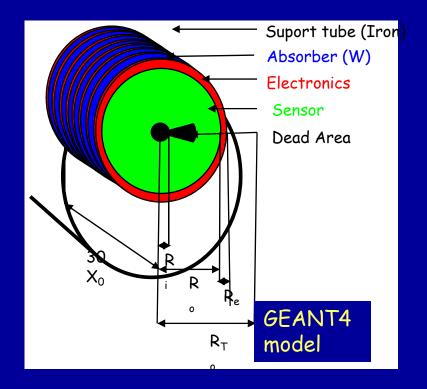
Difference in the Bhabha count rate:  $(1 \pm 2) \times 10^{-4}$ ; uncritical !

However: don't use the 'free space' for other purposes!





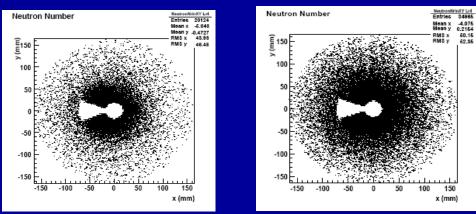
#### Radiation Dose and neutron fluxes



Electromagnetic dose for FE electronics:

### < 100 Gy /year

#### Neutron flux inside sensors:



Neutron flux through FE electronics:

10<sup>10</sup> neutrons/mm<sup>2</sup>/year

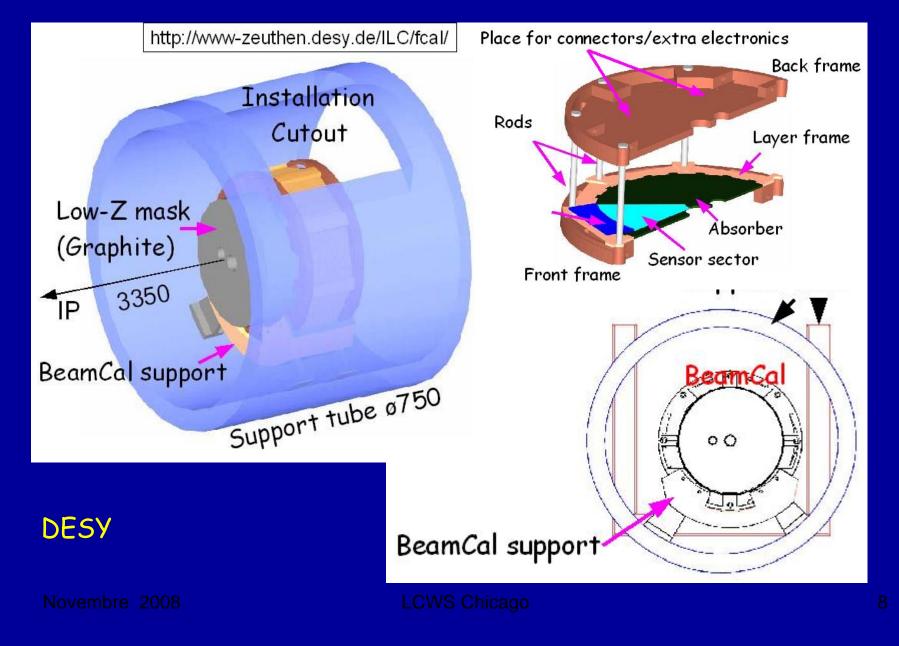
Two different 'physics lists'

10<sup>12</sup> neutrons/mm<sup>2</sup>/year (needs more detailed studies)





### **BeamCal Mechanics**





### Sensor R&D BeamCal

#### pCVD diamonds:

•radiation hardness under investigation (e.g. LHC beam monitors, pixel detectors) •advantageous properties like: high mobility, low  $\varepsilon_R = 5.7$ , thermal conductivity

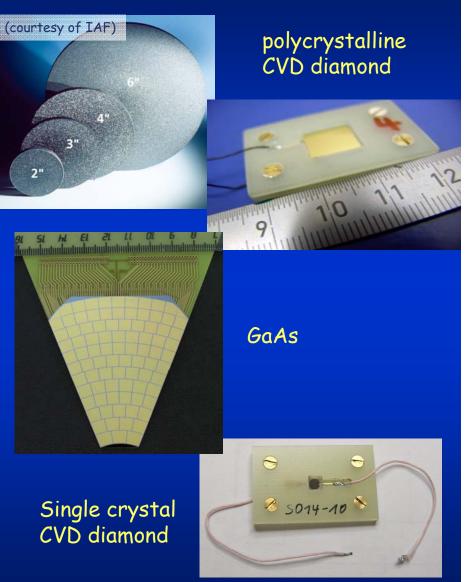
#### GaAs:

semi-insulating GaAs, doped with Sn and compensated by Cr
produced by the Siberian Institute of Technology

- SC CVD diamonds: •available in sizes of mm<sup>2</sup>
- Radiation hard silicon

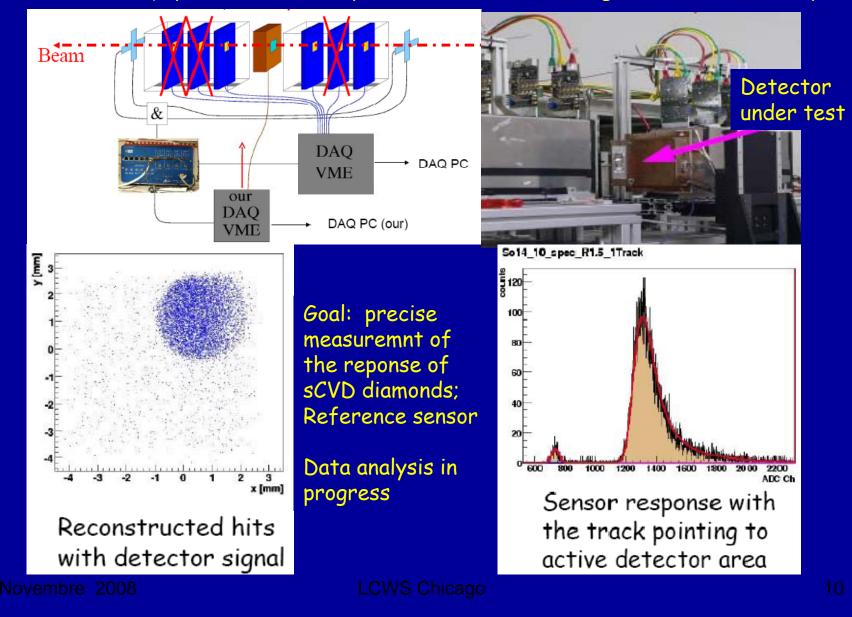
CVD: Chemical Vapor Deposition





#### Sensor Tests

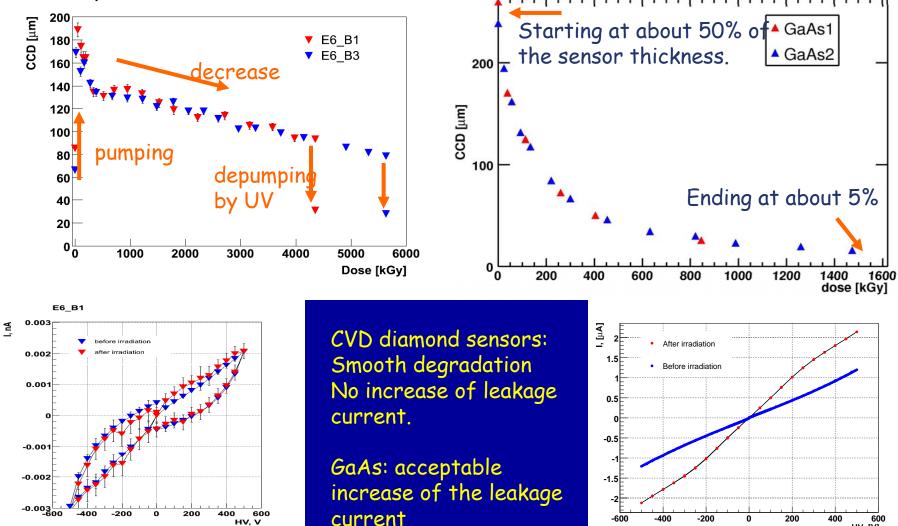
Testbeam equipment for sensor performance studies using the EUDET telescope





E6 samples CCD vs dose at 400V

ollabora

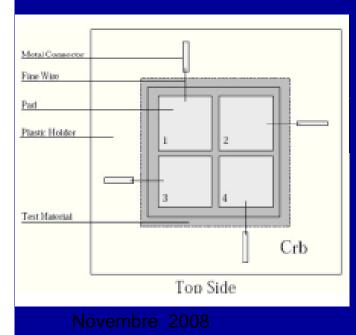


HV, [V]



### Sensor tests

A new batch of GaAs sensors with Cr concentrations between 10<sup>16</sup> and 10<sup>18</sup> was recently delivered, Lab tests completed



Sensors made of single crystal quartz and sapphire show promising sensitivity to ionising irradiation

> Testbeam investigations in December !



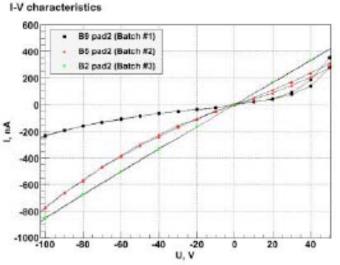
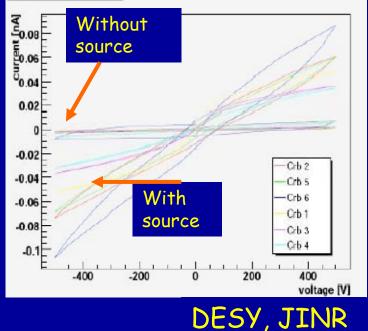


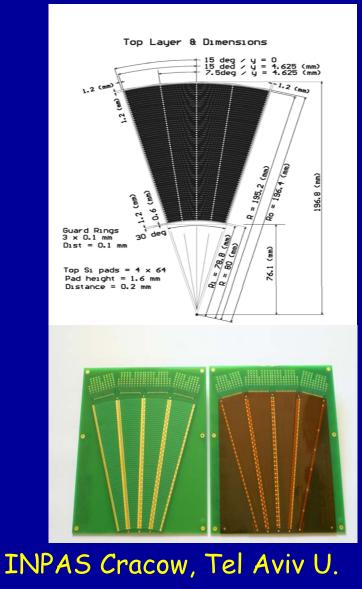
Figure 2. I-V characteristics for the sensors with different Cr concentration (linear part)

IV characteristics





### Sensor Production

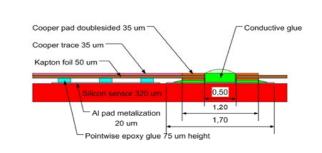


N-type silicon, p<sup>+</sup> strips, n<sup>+</sup> backplane, Crystal Orientation <100> 320  $\mu$ m thickness  $\pm$  15  $\mu$ m Strip pitch: 1800  $\mu$ m Strip p<sup>+</sup> width: 1600  $\mu$ m Strip Al width: 1700  $\mu$ m

Masks for prototypes ready (Hamamatsu)

Prototype sensors just ordered

In parallel: development of the fanout



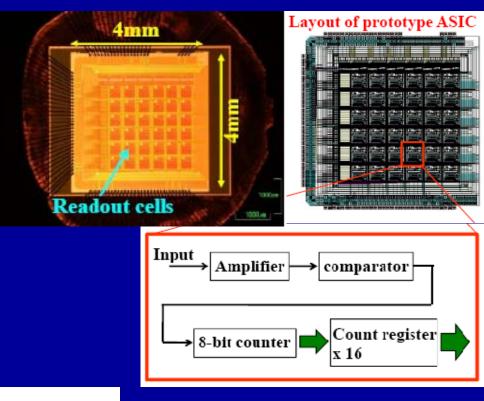
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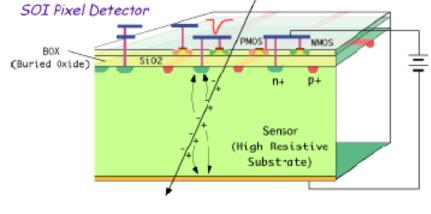


### **FE Electronics**

ASIC for the pair monitor .25 mm TSMC technology # of pixel: 36 Pixel size: 400 x 400 mm2 Bump bonding to a sensor

Prototype produced and successfully tested





Pair monitor will use SoI technology, Sensor and readout ASIC embeddd in the same wafer;

prototype 2009

Tohoku Univ.

Novembre 2008



### FE Electronics, LumiCal

•One FE ASIC will contain 32 - 64

channels, 10 bit

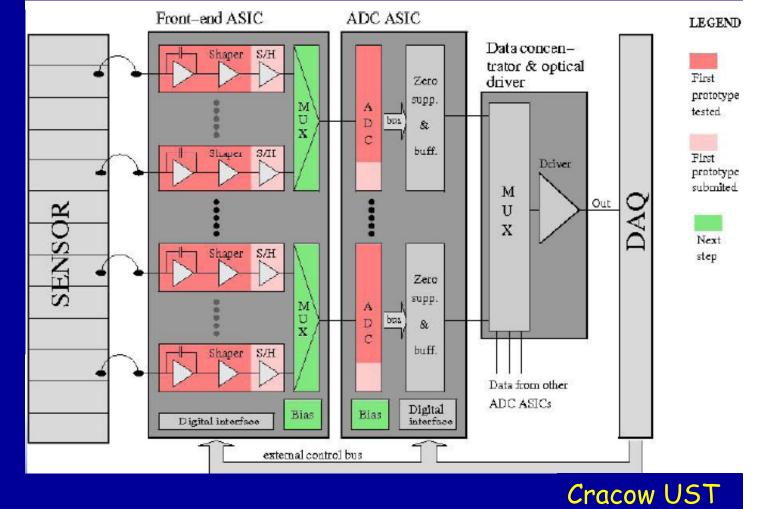
•One ADC will serve several channels (MC simulations not

finished) • AMS 0.35 μm

technology

 prototypes of the FE ASIC and ADC ASIC available,

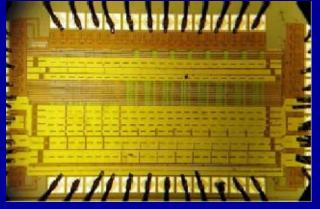
Tests of the FE ASICS so far promising.





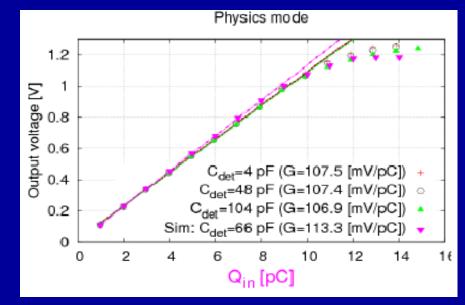
### FE Electronics, LumiCal

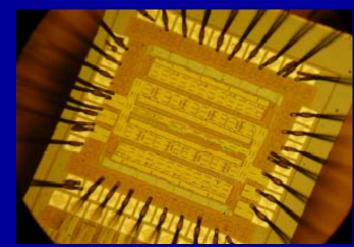
FE Asic: 8 channles per chip, 4 with MOS feedback resistance, 4 with passive Rf feedback



ADC Asic: •Pipeline architecture •10 bit resolution •Maximum sampling rate 35 MHz

First prototypes needed improvement, Submission ADC and DAC Sept. 2008 Prototypes expected Nov. 2008 Novembre 2008

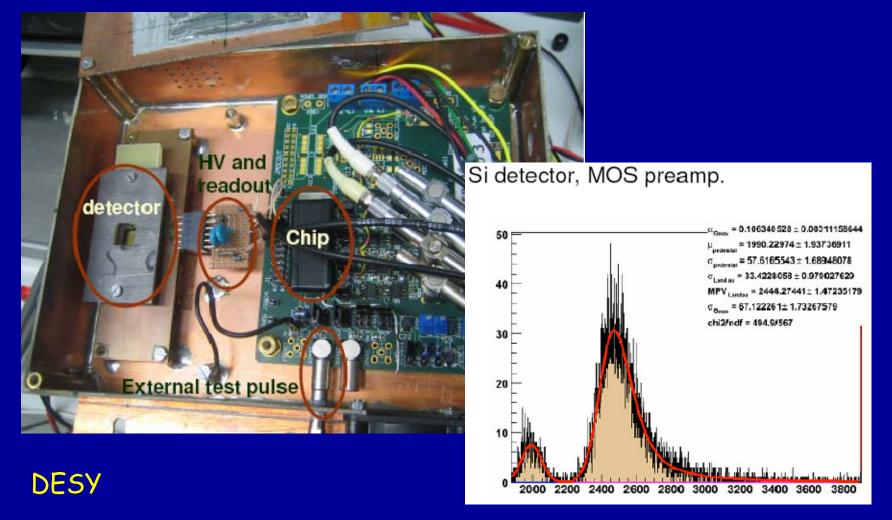






# FE Electronics, LumiCal

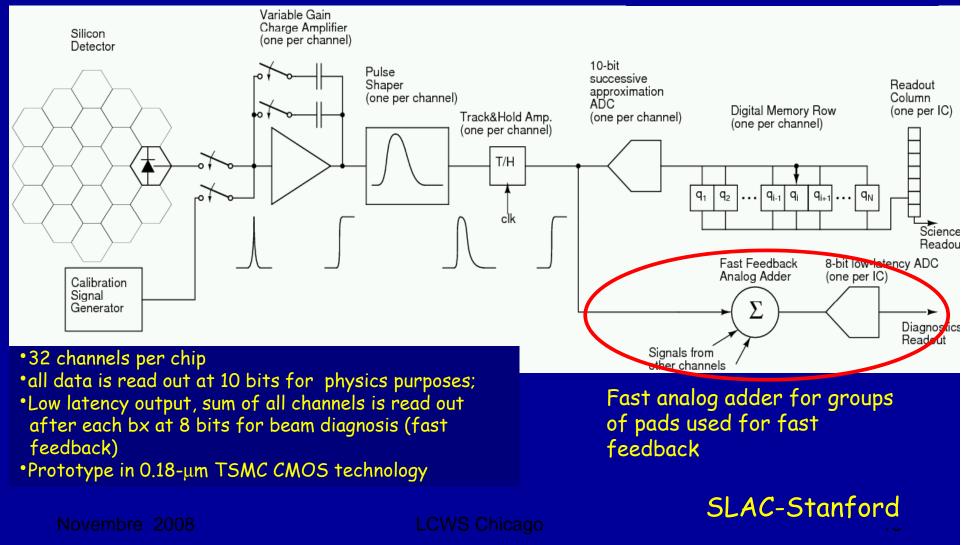
#### First successful tests of the analog part with a single pad sensor





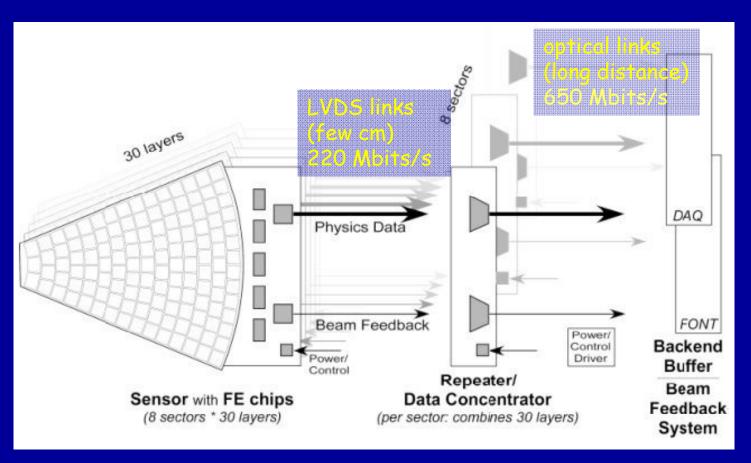
#### Dedicated FE electronics for BeamCal, based on KPiX (see talk by Herbst in the DAQ session)

Digital Buffering during bunch train, readout in between trains





## Data Transfer



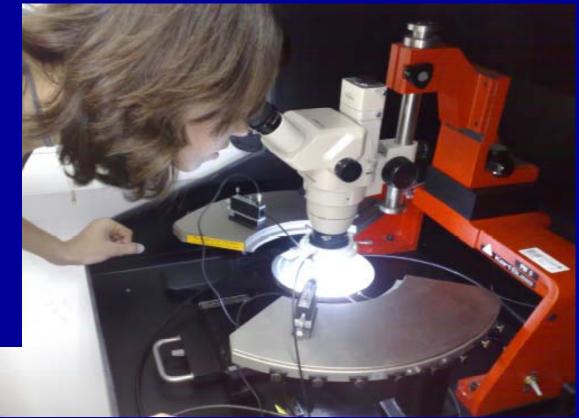
First step: concept based commercial components Second step: dedicated prototype for a system test

#### IKP TU Dresden



# Infrastructure

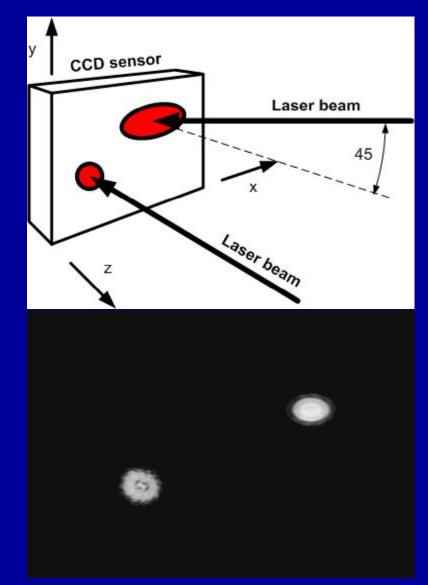
- A dedicated silicon lab is created in Tel Aviv:
- •Computer monitored prob station
- Computer supported I(V), C(V) measurements
- in preparation:
- clean room
- spectroscopic set-up



A dedicated HEP lab building is designed for detector R&D, planned to be ready mid 2009



# Laser Position Monitoring





Over short distances accuracies reached: Displacements in the x-y plane: +-0.5  $\mu$ m Displacements in z direction: +- 1.5  $\mu$ m

### INP PAS Cracow

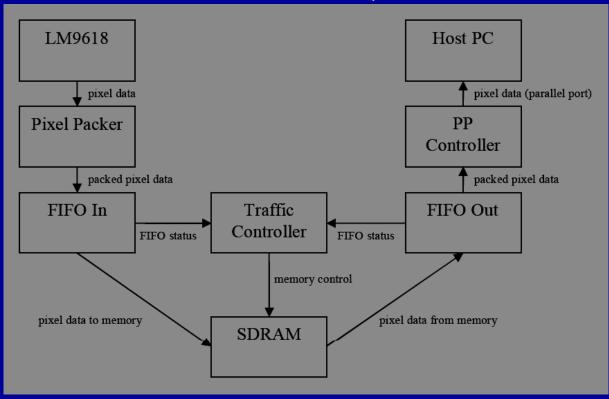
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#### Scheme of the readout and monitoring electronics

### Dedicated CMOS sensor

### **Displacement calculations**





# Priority topics within FCAL:

- Large area radiation hard sensors for calorimetry (BeamCal)
- Precise position measurement of electromagnetic showers (Sensors for LumiCal)
- ASICS with high readout speed, large dynamic range, large buffering depth and low power dissipation, allowing fast feedback for luminosity optimisation
- Prototyping and test of more complex subsystems



# backup



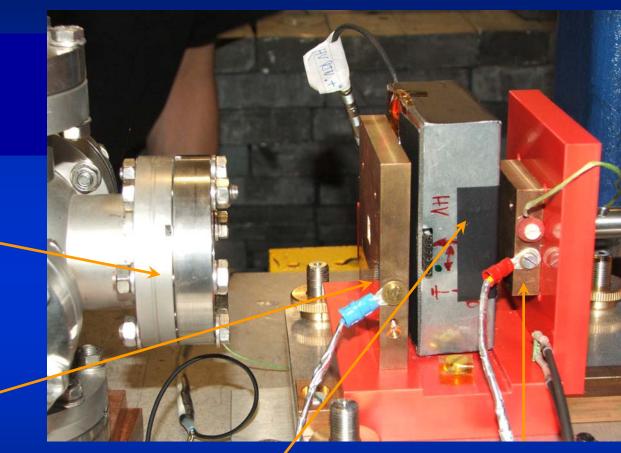
## Test Beam Equipment and sensor tests

Setup used for radiation hardness tests at the SDALINAC accelerator

TU Darmstadt

exit window\_ of beam line

collimator  $(I_{Coll})$ 



Faraday cup (I<sub>FC</sub>, T<sub>FC</sub>)

Completed and more comfortable: more efficient use of the beam

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LCWS Chicago

sensor box (I<sub>Dia</sub>, T<sub>Dia</sub>, HV)